

### Electronics component scheme scales up with Rs 41,863-crore approvals; projects spread across 8 states

The government has cleared 22 new proposals under the Electronics Component Manufacturing Scheme (ECMS) involving Rs 41,863 crore in investment, with projected production of Rs 2.58 lakh crore and 33,791 direct jobs, marking the largest tranche of approvals under the scheme so far, the Ministry of Electronics and Information Technology announced on January 2.

The latest clearances significantly widen the scale and scope of ECMS as India pushes to deepen domestic electronics manufacturing beyond final assembly.

The approved companies include Epitome Components, Deki Electronics, TDK India, Signum Electronics, India Circuits, BPL Limited, Wipro Global Engineering and Electronic Materials, Vital Electronics, Motherson Electronic Components, ATL Battery Technology (India), Tata Electronics, NPSP Advanced Materials, Yuzhan Technology (India), AT&S India, Ascent-K Circuit, Amphenol High Speed Technology India, Samsung Display Noida, Cipsa Tec India, Kunshan Q Tech Microelectronics (India), Dixon Electroconnect, Hindalco Industries, and Shogini Technoarts.

These include five bare components—printed circuit boards (PCBs), capacitors, connectors, enclosures and lithium-ion cells; three sub-assemblies—camera modules, display modules and optical transceivers; and three upstream supply-chain items such as aluminium extrusion, anode material and laminates.

Unlike earlier batches that were concentrated in a few states, the latest approvals are spread across eight states — Andhra Pradesh, Haryana, Karnataka, Madhya Pradesh, Maharashtra, Tamil Nadu, Uttar Pradesh and Rajasthan.

The expanded clearances build on earlier ECMS approvals, including a batch announced in October that cleared seven projects worth Rs 5,532 crore in investment, with an estimated Rs 44,406 crore in output and over 5,000 jobs, led by companies such as Kaynes Circuits, SRF, Syrma Strategic Electronics and Ascent Circuits. Those projects focused on high-value inputs like multi-layer and HDI PCBs, copper laminates, camera modules and polypropylene film, many of which were previously imported in bulk.

Last month, the ministry had also approved 17 additional projects worth Rs 7,172 crore, underscoring the accelerating pace of clearances as the government works through a large pipeline of applications.

ECMS was notified in April last year to address India's heavy dependence on imported electronic components and materials. The scheme has seen strong industry response, with the ministry earlier disclosing that it had received 249 applications involving proposed investments of Rs 1.15 lakh crore, nearly double the scheme's original investment target of Rs 59,350 crore.

The government has positioned ECMS as a key complement to production-linked incentive (PLI) schemes for mobile phones, IT hardware and telecom, aiming to improve domestic value addition, secure supply chains and reduce import dependence for critical components.

Further approvals are expected in subsequent batches, including in capital equipment and advanced materials, as India seeks to move from being an electronics assembly base to a full-stack electronics manufacturing hub.

**Source:** <https://www.moneycontrol.com/news>

## **Amber Group receives Rs 4700 crores Investment PCB manufacturing clearance under ECMS for Atmanirbhar Bharat**

- ❖ **Amber Group's Ascent Circuits received Rs 991 crore investment approval to set up a high-volume, multilayer PCB manufacturing facility in Hosur, Tamil Nadu, expected to commence operations between Q4 FY26 and Q1 FY27**
- ❖ **Ascent-K Circuit, a JV with Korea Circuits, in the third round has received investment approval of Rs 3,215 crores at the EMC 2.0 cluster, YEIDA for advanced PCB manufacturing, including HDI and flexible PCBs**
- ❖ **Shogini Technoarts (a subsidiary of IL JIN Electronics, a step-down subsidiary of Amber Enterprises) also secured approval in the ECMS for an investment of Rs 500 crores.**

Marking a significant step in strengthening India's domestic electronics and printed circuit board (PCB) manufacturing capabilities, Amber Enterprises India Limited announced that its group companies have received combined approvals, at a value of over Rs 4700 crores investment under the Government of India's Electronics Components Manufacturing Scheme (ECMS).

Under these approval, Amber Group has invested across three strategic initiatives under the ECMS framework, aimed at reducing India's PCB import dependency and deepening localization of components across the EMS value chain.

In the first tranche of approval on October 27th, 2025, Ascent Circuits, a wholly owned subsidiary of Amber Group, has received approval for an investment of Rs 991 crore to set up a high-volume, multilayer PCB manufacturing facility in Hosur, Tamil Nadu. The facility will cater to growing demand from consumer electronics, industrial, automotive, telecom and other emerging segments. The construction for this plant is well underway with manufacturing expected to be between Q4 FY26 and Q1 FY27.

The latest tranche of approval, on January 2nd 2026, marks a significant milestone for the company as Amber's joint venture with Korea Circuit, Ascent-K Circuit, focused on advanced PCB manufacturing, including HDI and flexible PCBs, has received ECMS approval for an investment of Rs 3,215 crore at the EMC 2.0 cluster in the Yamuna Expressway Industrial Development Authority (YEIDA), Uttar Pradesh. This project has further been granted a green flag by the Cabinet Committee of Uttar Pradesh.

Boosting this, Shogini Technoarts (a subsidiary of IL JIN Electronics, a step-down subsidiary of Amber Enterprises) also secured approval in the ECMS for an investment of Rs 500 crores.

Collectively, these projects form part of the ECMS-approved EMS manufacturing and capacity building under MeitY and underscore Amber Group's long-term commitment to building resilient electronics supply chain for an Atmanirbhar Bharat.

Marking this milestone, Mr Jasbir Singh, Executive Chairman & CEO, Amber Group, said, "We sincerely thank the Government of India and the Ministry of Electronics and Information Technology for the continued support and timely clearances under the ECMS scheme. These approvals reinforce our confidence in India's electronics manufacturing vision. With over Rs 4,700 crore being invested across PCB manufacturing and advance electronics components, Amber Group is committed to meaningfully reducing import dependency, building scale and capability within the country, and contributing to the Atmanirbhar Bharat mission."

As India accelerates its ambition to become global electronics manufacturing hub, Amber Group's ECMS-backed investments are expected to generate significant employment, enable technology transfer, and strengthen India's position in high-value electronics and component manufacturing.

**Source: <https://konexionetwork.com/business-news>**

## **Indian PCB Market to Grow to \$24.7 Billion by 2033, Driven by 5G, EVs, and 'Make in India' Push**

IMARC Group has published a new market research report on the Indian PCB (Printed Circuit Board) Market. This report provides an in-depth analysis of the industry, featuring insights into the market. It encompasses competitor and regional analyses, as well as recent advancements in the market.

**Indian PCB (Printed Circuit Board) Market Size & Future Growth Potential:**

The Indian PCB (printed circuit board) market size was valued at USD 6.3 billion in 2024 and is projected to grow to USD 24.7 billion by 2033, with an expected compound annual growth rate (CAGR) of 15.58% from 2025 to 2033.

Transformations in the Indian PCB market are propelled by the adoption of new consumer technologies as well as Indian electronic manufacturing. Increasing focus on compact, high-performance handheld devices like smartphones and other IoT gadgets is stimulating demand for high-density interconnect (HDI) PCBs. Moreover, the rise of 5G technology is driving the need for advanced PCBs designed to handle higher frequencies and data transfer speeds. Domestic imports are being simplified by the "Make in India" initiative, further enhancing PCB production within the country.

**Source: <https://www.pcbdirectory.com/news>**

## India needs 10-12 new big PCB units with ₹ 20K cr investment to cut reliance on imports

India needs to attract 10-12 big, printed circuit board producers over the next five years with an investment of ₹ 20,000 crore to reduce dependence on imports and avoid disruptions, electronics industry body ELCINA said in a report.

The report shared with the government in September estimates that the total PCB (printed circuit board) demand in India for the fiscal year 2024–25 was ₹ 35,000 crore, approximately \$ 4.2 billion, out of which 88 % of the requirement was met through imports predominantly from China, Taiwan, South Korea, and select Southeast Asian countries.

India must address the rising demand by setting up 10–12 new large PCB units, each with a one million square meter capacity, alongside 2–3 million square meters of Flex/Rigid Flex units over the next five years. This expansion will require investments worth ₹ 20,000 crore and is projected to generate annual revenues of ELCINA said that the electronic components manufacturing scheme (ECMS) has been exceptionally well received by industry stakeholders, with numerous large-scale projects having already been submitted for application and awaiting approval.

"Additionally, there are reports of some ecosystem participants establishing raw material production units in CCL (copper clad laminate). Collectively, these developments indicate a growing and optimistic outlook for the Indian PCB sector industry," the report said ₹ 20,000 crore," the report said.

**Source:** <https://www.msn.com/en-in/money>

### India PCB Manufacturing: Reduce Import Reliance

Based on the government's target to create a component manufacturing base of USD 150 billion by 2030, the PCB is expected to contribute approximately 9-10 per cent of the total value which comes to around USD 14 billion by the fiscal year 2030.

"Realizing this growth will necessitate nearly a threefold expansion of India's domestic PCB manufacturing capacity over the next six years, supported by private sector investments and policy-driven incentives," the report said.

The report said establishing new facilities will have substantial downstream effects. It will provide direct employment opportunities for 20,000 individuals and create indirect jobs for up to 75,000 more along the value chain, fostering a robust support system for start-ups and research and development institutions that currently rely on imports due to the lack of local quality PCB suppliers.

Mobile devices dominated the demand for PCB in FY 2025 with an impressive 52 per cent share of total market value while representing only 10 per cent of production volume indicating demand for premium PCBs in the segment.

The consumer electronics sector used 16 per cent of total production volume and 12 per cent of market value. It was followed by automotive electronics with consumption of 7 per cent of production volume and 5 per cent of PCB market value in fiscal year 2025.

Industrial electronics dominated PCB usage by volume, accounting for 42 per cent of all boards produced, yet contributed only 10 per cent of market value.

The telecommunications electronics sector accounts for 6 per cent of PCB production volume and 7 per cent of market value in fiscal year 2025, reflecting a balanced contribution to both volume and revenue, the report said.

**Source:** <https://money.rediff.com/news>

## India's bare PCB manufacturing set for 45% CAGR surge

The bare PCB market in India currently is worth \$5 billion, with an 88% import dependence. Domestic production is expected to expand from \$0.6 billion in fiscal 2024 to \$3.8 billion by FY29, reducing the dependence on supplies from abroad to 69%, the financial services firm said in the report.

**Source:** <https://economictimes.indiatimes.com/>

## Key Trends in the Global PCB Industry by the End of 2025

In November and December 2025, the global PCB industry will undergo a period of intensive policy adjustments. The US and Europe will focus on supply chain security and environmental upgrades, Southeast Asia and India will intensify their efforts to attract production capacity, and Japan and South Korea will strengthen their technological support. The interplay of multiple policies will accelerate the industry's transformation towards "compliance, regionalization, and high-end development," highlighting four key trends.

### Trade policies are simultaneously "buffering and tightening," accelerating supply chain restructuring

Global trade policies are exhibiting a "differentiated adjustment" characteristic, directly impacting PCB companies' capacity layout strategies:

**US tariff exemption extension + control buffer:** On November 28, the US extended tariff exemptions for 178 PCB-related products to November 2026, covering high-end PCBs such as AI servers and communication equipment. Companies like Shenghong Technology and Shiyun Circuits directly benefit (due to low export ratios to the US and product exemptions). Simultaneously, the BIS suspended the "50% penetration rule" for one year, providing a buffer for the supply chain, but the strengthened export controls still indirectly restrict the flow of high-end PCB technology.

**Strengthened regional trade rules:** The US included Thailand in its "reciprocal tariff list," reducing the nominal tariff rate to 19%, but imposing a 40% punitive tariff on "transshipment circumvention" products, forcing companies to standardize the origin management of their Southeast Asian production capacity. Meanwhile, the RCEP and the China-ASEAN Free Trade Agreement continue to exert their influence, with China's PCB exports to ASEAN reaching US\$6.8 billion in 2024 (+15.6%), further reducing trade costs within the region.

## **Environmental compliance becomes a "hard constraint," and globally unified standards are rapidly taking shape**

From November to December, a series of environmental policies in Europe and the United States were implemented, propelling the PCB industry into a “mandatory era of green manufacturing”:

Major revisions to the EU RoHS Directive: Three revised directives were released in November, adjusting the exemption clauses for lead in alloys and high-temperature solders, requiring companies to conduct compliance assessments again, and increasing the cost of alternative material testing and life cycle assessment (LCA) by 3-5%. Simultaneously, the revised WEEE requires PCB products to meet the recyclability principle (DfR), including modular design and easily recyclable soldering, making compliance a prerequisite for international orders.

Extended impact of carbon tariffs: The EU CBAM carbon tariff has been expanded to the electronics manufacturing industry, threatening the elimination of traditional high-pollution PCB processes. Lead-free and low-VOC production has become the global standard. China’s GB26572-2025 standard is aligning with international standards, promoting the collaborative upgrading of environmental technologies across the industry.

## **Southeast Asia's "Policy Dividends" Explode, Becoming a Core Destination for Global Production Capacity Transfer**

Southeast Asian countries like Thailand and Vietnam are attracting global PCB companies to concentrate their operations through enhanced policies:

- **Thailand’s Incentive Policies Upgraded:** On November 6th, the Thai Board of Industry and Commerce (BOI) included raw materials such as copper clad laminate (CCL) and flexible copper clad laminate (FCCL), as well as processes like lamination and drilling, in its incentive program, offering up to 8 years of corporate income tax reductions and import tax exemptions for equipment. This has already attracted over 200 billion baht in investment, with 9 companies including Huatong Computer and Shenghong Technology establishing factories, expected to release high-end production capacity by 2026. In December, Chaoying Electronics invested an additional \$100 million in its Thai base, focusing on expanding AI computing power PCB production, highlighting the policy’s attractiveness.
- **Vietnam’s Stricter and Balanced Regulations:** While absorbing low-to-mid-end PCB production capacity, Vietnam is strengthening its re-export inspections, detaining multiple batches of “simply assembled” electronic components to prevent tariff circumvention and promote the industry’s upgrade to “full-chain manufacturing.”

## **Technological Innovation Subsidies Focus on High-End Industries, Japan, South Korea, and India Lead Domestic Breakthroughs**

Policies in various countries are tilting towards the high-end PCB sector, with a focus on supporting semiconductor components and PCB technologies for AI servers:

- **Japan's 100 billion Yuan Subsidy Drives High-End PCB Development:** The Ministry of Economy, Trade and Industry continues its support for the semiconductor industry. Shinko Electric Industries received a subsidy of 920 million yuan for the research and development of a new generation of FC-BGA substrates. This product is suitable for the heterogeneous integration needs of AI chips, and the market gap continues to widen. Japan's total semiconductor-related subsidies exceeded 2 trillion yen for the year, indirectly driving the growth in demand for high-end PCB materials.
- **South Korea's 700 trillion Won Chip Cluster Development:** In December, a long-term plan was announced, incorporating PCBs into the key links of the semiconductor industry chain. It requires national security infrastructure to prioritize the procurement of domestically produced PCB products, strengthening the self-sufficiency and control of the high-end supply chain.

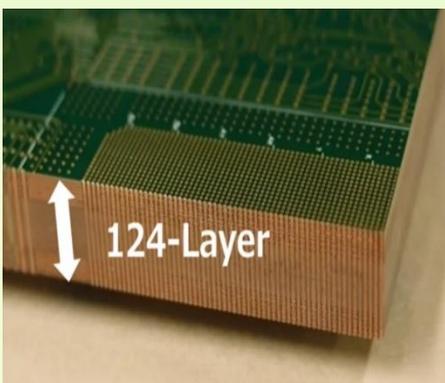
### **Policy-Driven Industry Transformation and Responses**

The global PCB policy landscape at the end of 2025 essentially reflects the dual goals of “supply chain security” and “technology upgrade”: Europe and the US are setting entry barriers through environmental and tariff policies, Southeast Asia and India are absorbing capacity transfers with preferential policies, and Japan and South Korea are focusing on breakthroughs in high-end technologies. For companies, three key directions need to be grasped:

- **Compliance First:** Proactively plan for lead-free and low-VOC processes to meet globally unified environmental standards.
- **Capacity Diversification:** Leverage Southeast Asian policy benefits to build a “China + 1” layout and mitigate trade risks.
- **Technology Positioning:** Focus on high-end areas such as high-multilayer PCBs for AI servers and FC-BGA substrates to secure policy subsidies and market advantages.

**The global PCB industry is transitioning from “scale expansion” to “quality competition,” and policy will be the core driving force for the restructuring of the industry landscape in the next 2-3 years.**

### **OKI Reaches New Heights With a 124-Layer PCB**



**The 124-layer printed circuit board surpasses the longstanding 108-layer industry ceiling without increasing the standard board thickness of 7.6 mm.**

**The jump from 108 to 124 layers may appear marginal on paper, but within the precision-driven world of PCB fabrication, it marks a fundamental shift in what's possible. The 15% increase in signal layer count was achieved without increasing the standard 7.6-mm board**

**thickness, a limit imposed by existing form factor constraints in wafer-level test equipment.**

**Source:** <https://www.allaboutcircuits.com/news/oki-reaches-new-heights-with-124-layer-pcb/>



29 30 31 July 2026 | Hall no 14, Bharat Mandapam New Delhi

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## AN EXPO FOR THE GROWTH OF INDIAN ELECTRONICS INDUSTRY

With immense pride and boundless excitement, I, as the **President** of the **Indian Printed Circuit Association**, extend a warm invitation to the **18th edition of IPCA Electronics Expo India 2026**—an extraordinary event set to illuminate the future of the PCB and electronics industry from **July 29th to 31st** at the iconic **Bharat Mandapam, Hall No. 14, Pragati Maidan, New Delhi**.

This is more than an expo—it is a defining movement, a catalyst placing India firmly on the global map of innovation, technology, and excellence.

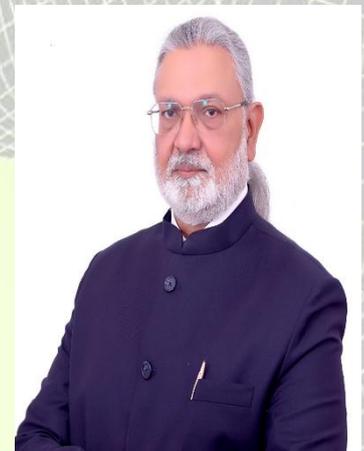
To the visionary leaders driving progress across Indian and international industries: this is your moment to chart the future. Showcase revolutionary solutions, build transformative partnerships, and gain front-row insight into the megatrends shaping the world of tomorrow. Don't just participate, lead.

To global investors and innovators: discover India's unparalleled potential. Powered by the ambitious 'Make in India' initiative and a supportive government fostering ingenuity and growth, your investments here represent not uncertainty, but unstoppable opportunity. Join the manufacturing renaissance that is transforming India into a global powerhouse of technology.

To our vibrant community of SMEs: this expo is your launchpad. Connect with influential decision-makers, discover strategic collaborations, and propel your enterprise to new heights. Let this be your turning point toward greatness.

To the professionals, manufacturers, suppliers, and trailblazers who define our industry: the IPCA Electronics Expo India 2026 is your platform for advancement, knowledge, and inspiration. Engage with cutting-edge ideas, network with thought leaders, and return empowered to lead innovation in your domain.

Seize this moment and be part of a defining chapter in India's technological evolution. Together, we will shape the future, foster prosperity, and celebrate the spirit of fearless innovation. **The journey begins here—at the IPCA Electronics Expo India 2026.**



**Rajneesh Garg**  
President, IPCA

## International Events

 <p><b>APEX EXPO 2026</b> by Global Electronics Association</p>	<p><b>IPC APEX EXPO</b> March 17 -19, 2026 Anaheim Convention Center</p>
	<p><b>CPCA Show 2026</b> 24 -26 March 2026 NECC National Exhibition and Convention Center, Laigang Road Shanghai (CN)</p>
	<p><b>JPCA Show 2026,</b> 10-12 June 2026 The Tokyo Big Sight convention center in Tokyo, Japan.</p>
	<p><b>THECA SHOW 2026</b> 26-28 August 2026 BITEC EH 98-99, Bangkok Thailand</p>
	<p><b>KPCA SHOW 2026</b> 9-11 September 2026 Songdo Convensia Convention Center, Incheon, South Korea</p>
	<p><b>TPCA SHOW 2026</b> Oct 20 - Oct 22, 2026 Taipei Nangang Exhibition Center, Taipei, Taiwan</p>
	<p><b>CPCA SHOW PLUS</b> October 28 – 30, 2026 Shenzhen World Exhibition &amp; Convention Center</p>
	<p><b>HKPCA SHOW 2026</b> 2-4 Dec 2026 Shenzhen World Exhibition &amp; Convention Center (Bao'an)</p>

## Domestic Events

	<p><b>IPCA Electronics Expo India 2026</b> July 29th to 31st at Bharat Mandapam, Hall No. 14, Pragati Maidan, New Delhi</p>
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